Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

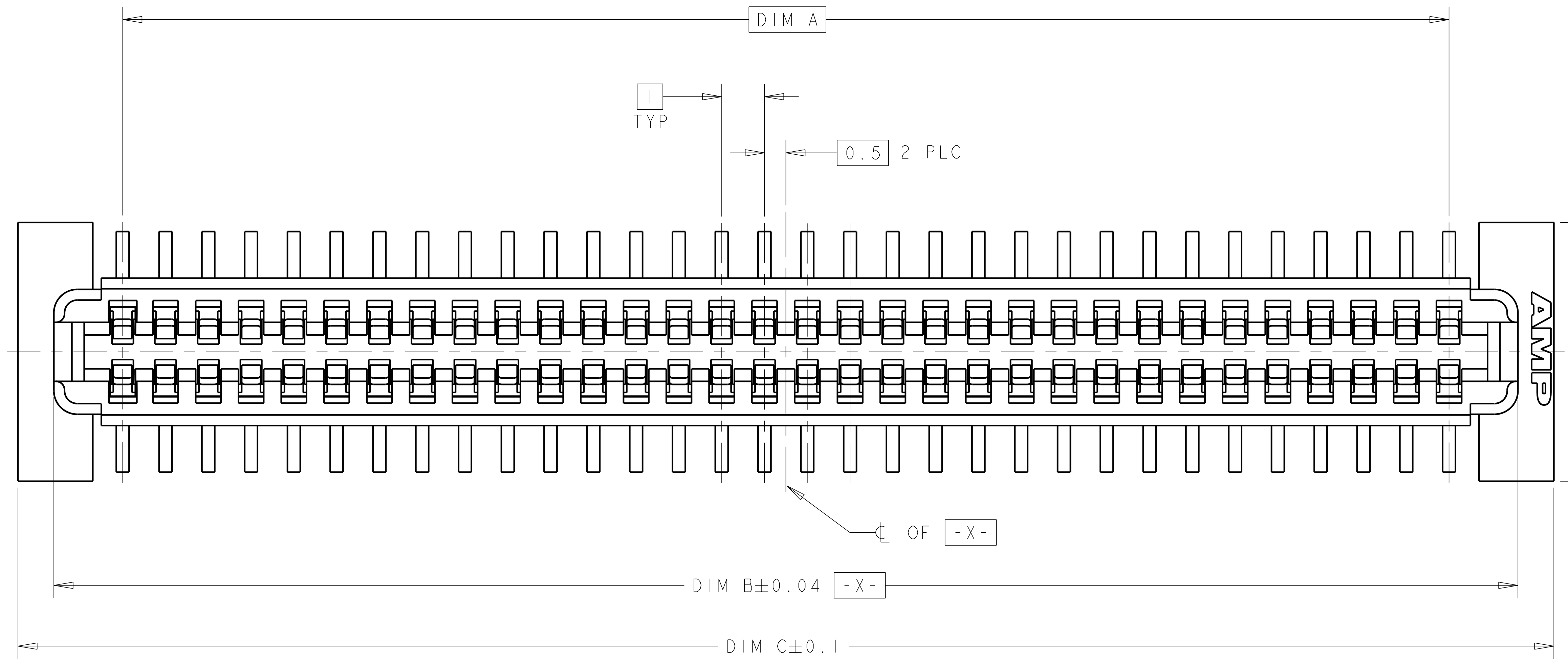
Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

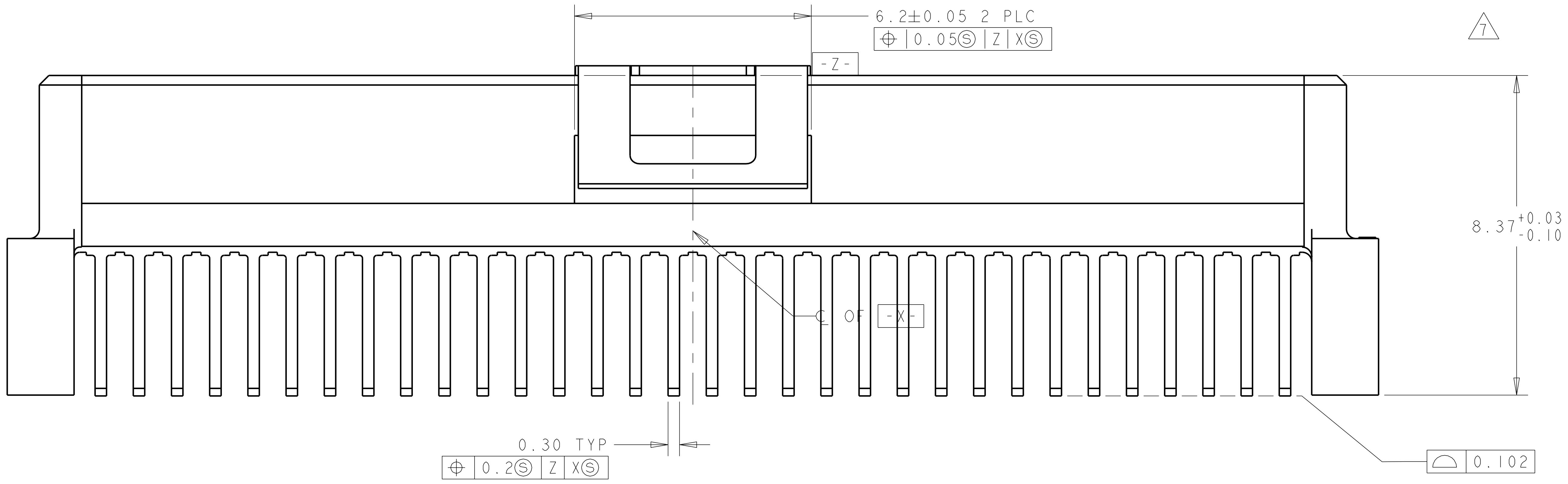
LOC	DIST
AD	00

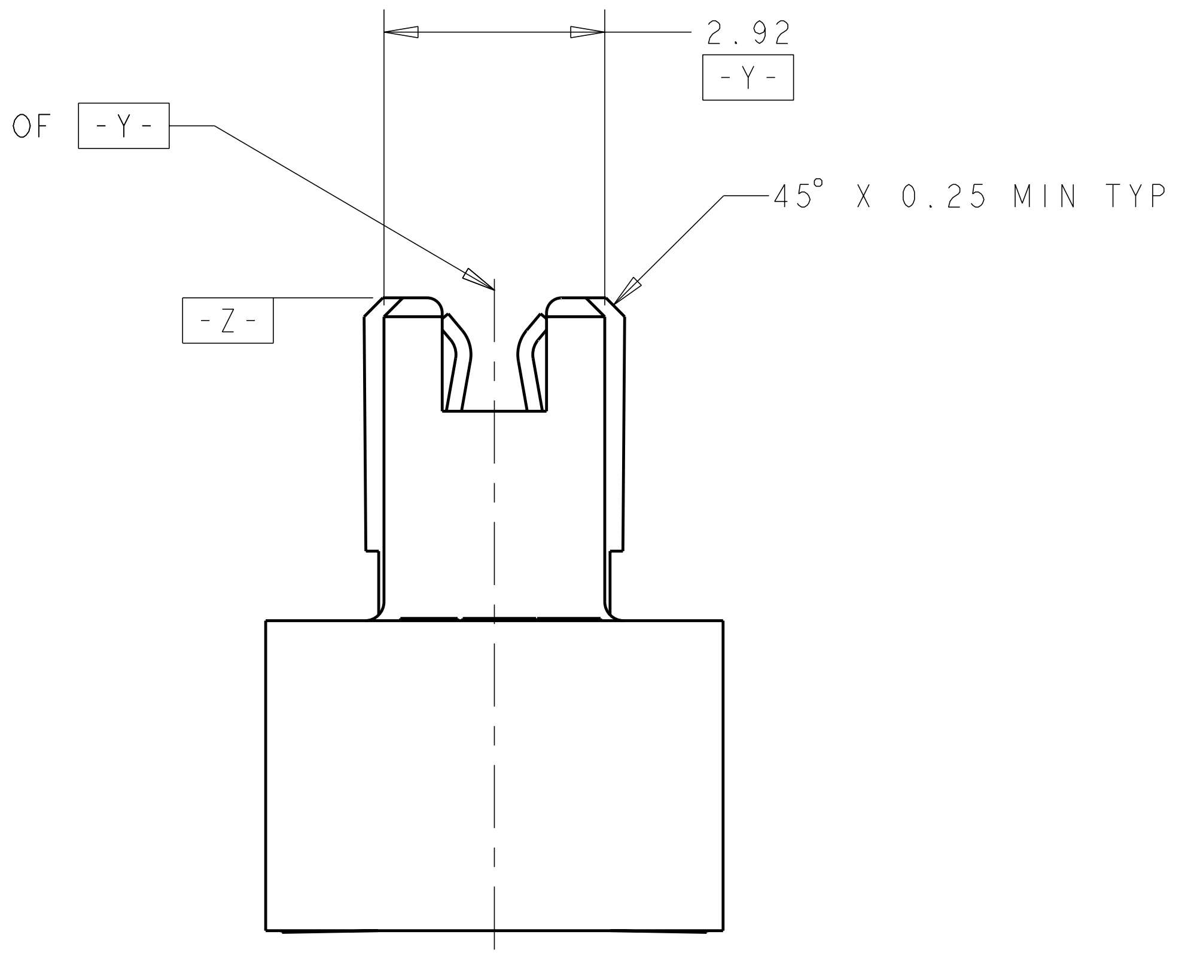
REVISIONS

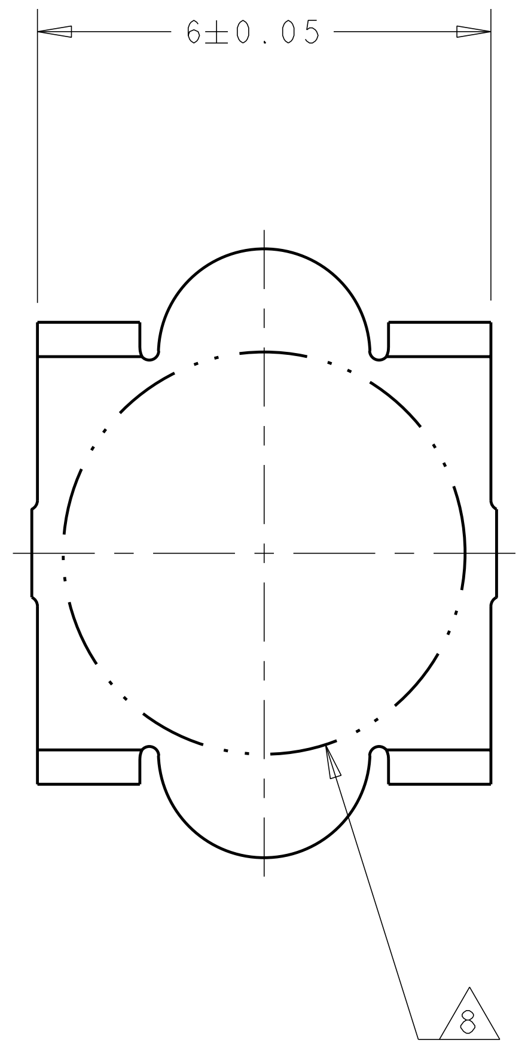
P	LTR	DESCRIPTION	DATE	DWN	APVD
	O	REV PER EC 0S12-0235-04	30SEP2004	BC	RW
	A	REVISED PER ECO-08-008615	10JUL2008	DH	DB



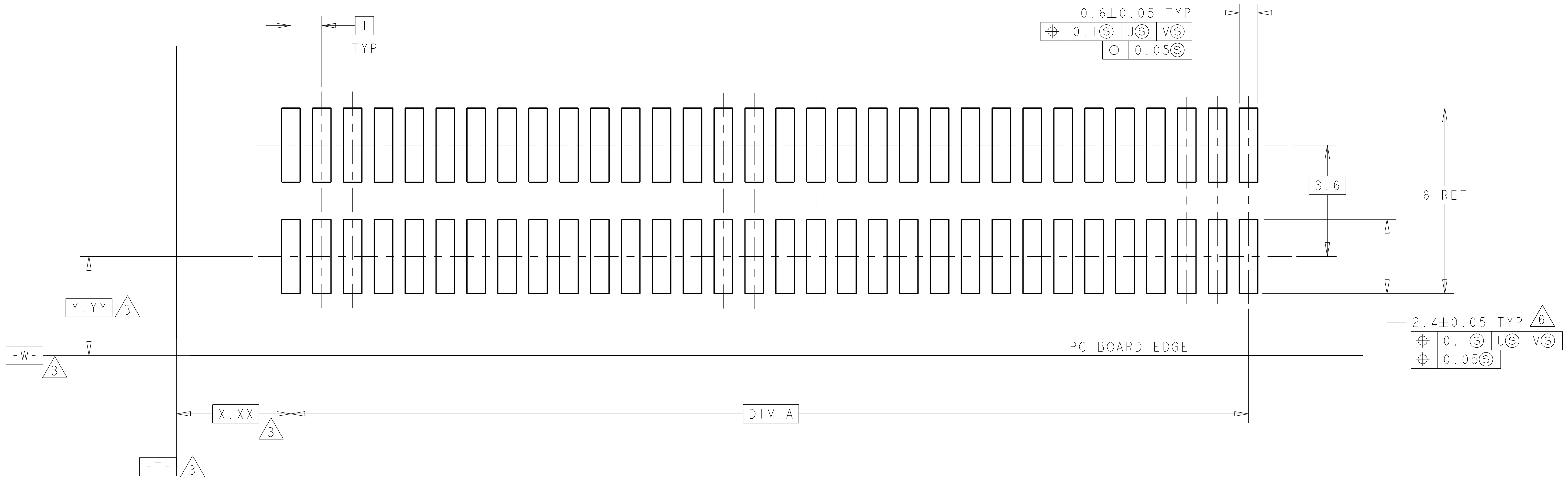
1. HOUSING MATERIAL: HIGH TEMPERATURE THERMOPLASTIC, COLOR: BLACK. CONTACT MATERIAL: PHOSPHOR BRONZE.
2. CONTACT FINISH: NICKEL UNDERPLATE ALL OVER, MATING SURFACES PLATED TO MEET PLI PERFORMANCE REQUIREMENTS OF INDUSTRY SPECIFICATION EIA-700AAAB, SOLDER TAILS PLATED TIN.
3. DATUM LOCATIONS AND BASIC DIMENSIONS TO BE ESTABLISHED BY THE CUSTOMER. CONSULT AMP ENGINEERING WHEN PLACING MULTIPLE CONNECTORS ON A PC BOARD.
4. PACKAGED IN TAPE ON REEL PER EIA-481.
5. VACUUM COVER DESIGNED FOR 4mm DIA. NOZZLE. COVER TO BE REMOVED AFTER SOLDERING. VACUUM COVER OMITTED FROM SOME VIEWS FOR DIMENSIONAL CLARITY.
6. SHORTER SOLDER LANDS MAY BE USED PER EIA 700AAAB, HOWEVER 2.4 LENGTH ASSURES OPTIMUM SOLDER FILLET REGARDLESS OF MANUFACTURER OF CONNECTOR.
7. REFERRED TO AS DIM H = 8.3±0.1 IN EIA 700AAAB SPECIFICATION.
8. 5.5 MIN DIAMETER TARGET AREA FOR VACUUM PICK-UP.
9. CONTACT FINISH: 0.00381 MINIMUM MATTE TIN PER ASTM B 545 ON SOLDER AREA, 0.00127 MINIMUM GOLD PER ASTM B 488 ON MATING AREA, BOTH OVER 0.00127 MINIMUM NICKEL PER SAE-AMS-QQ-N-290 ON ENTIRE CONTACT.







VACUUM COVER



RECOMMENDED PC BOARD LAYOUT

FINISH	DIM C	DIM B	DIM A	MATING CONNECTOR	STACK HGTS	POS	PART NO
9	45.9	44.22	41	5120534-2	13	84	1-5120530-2
9	35.9	34.22	31	5120534-1	13	64	1-5120530-1
2	45.9	44.22	41	5120534-2	13	84	5120530-2
2	35.9	34.22	31	5120534-1	13	64	5120530-1

THIS DRAWING IS A CONTROLLED DOCUMENT FOR TYCO ELECTRONICS CORPORATION IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION SHOULD BE CONTACTED FOR THE LATEST REVISION.

DWN B.CARBO 30SEP04
CHK R.WERTZ 30SEP04
APVD R.WERTZ 30SEP04

tyco Electronics
Tyco Electronics
Harrisburg, PA 17105-3608

DIMENSIONS: mm

TOLERANCES UNLESS OTHERWISE SPECIFIED:
0 PLC ±-
1 PLC ±-
2 PLC ±0.03
3 PLC ±0.003
4 PLC ±-
ANGLES ±0°-1′

PRODUCT SPEC 502-1079
APPLICATION SPEC 114-25045
WEIGHT -

NAME
RCPT ASSY,W/COVER,1.0mmFH(IEEE1386)
CONNECTOR

MATERIAL 1
FINISH - SEE TABLE

SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO
A1	00779	C-5120530	-

CUSTOMER DRAWING
SCALE 10:1
SHEET 1 OF 1
REV A